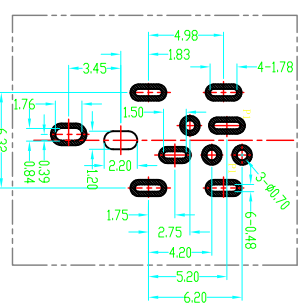
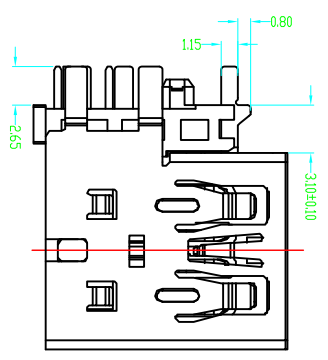
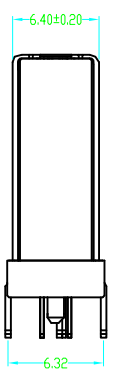
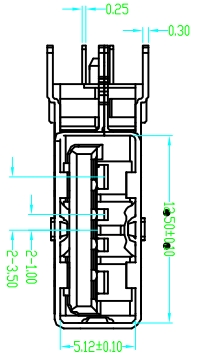
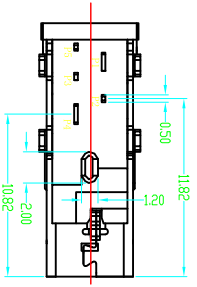
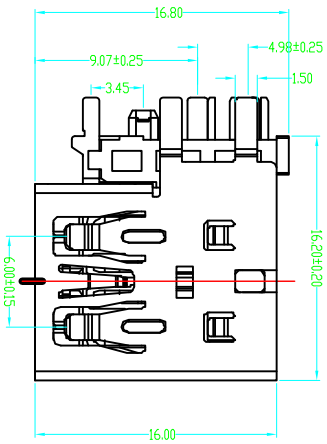
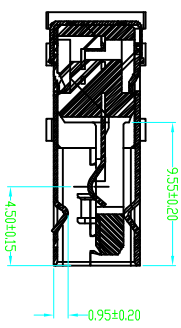


MAPX	MODIFICATION	DATE
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NOTES:

- MATERIALS AND FINISHES:**
 HOUSING MATERIAL: LCP R845 UL94V-0 HR.
 PIN MATERIAL: C7035 TM-04 T=0.25mm
 CONTACT AREAL: PLATING Au30u" min. Ni 80u" Min
 SOLDER TAIL: MATTE TIN 180u" Min
 SHELL MATERIAL: PHO. BRONZE T=0.30mm
 PLATED Ni 50u" MIN
 BACKSHELL MATERIAL: SUS304 T=0.20mm
- ELECTRICAL CHARACTERISTICS**
 CONTACT RESISTANCE: 30m Max.
 DIELECTRIC WITHSTANDING VOLTAGE: AC 500V R.M.S,
 INSULATION RESISTANCE: 1000M MIN
- MECHANICAL CHARACTERISTICS:**
 CONTACT INSERTION FORCE: 35 N MAX
 CONTACT SEPARATION FORCE: 10 N MIN(AFTER CYCLE 1500)
- MATERIAL MUST FULFILL GM74-11 SALCOMP HAZARDOUS SUBSTANCES MANAGEMENT STANDARD LATEST VERSION.**

产品图
PRODUCT CHART DWG

深圳市精拓金电子有限公司

公差一览表		单位	制图	许梅强	制图料号
TOLERANCE UNLESS OTHERWISE		UNITS	DRAWING	审核	PRODUCT PART NO
X ±0.15	X	±5.°	MM	郭治富	产品名称
X ±0.10	X	±2.°	1:1	黄国荣	PRODUCT NO
XX ±0.05	XX	±1.°	DATE	日期	USP AF SIDE 90°
XXX ±0.03	XXX	±0.5°	2016-09-09	核准	DIP TYPE
				APPD	版本
				VIEW	AD

1 2 3 4 5 6 7 8 9 10